

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.29983	100.0	17.9
			Subtotal	0.29983	100	17.9
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.17421	100.0	10.4
			Subtotal	0.17421	100	10.4
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01396	5.0	0.83325
	Lead alloy	Silver (Ag)	7440-22-4	0.00698	2.5	0.41662
	Lead alloy	Lead (Pb)	7439-92-1	0.25821	92.5	15.41512
			Subtotal	0.27915	100	16.66499
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36851	100.0	22
			Subtotal	0.36851	100	22
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02005	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06683	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.74768	99.87	3,984.813
			Subtotal	66.83456	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.08284	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.127	16.0	306.08
	Filler	Silica fused	60676-86-0	22.75105	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.08284	6.5	124.345
			Subtotal	32.04373	100	NaN
			Total	99.99999	100	NaN

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